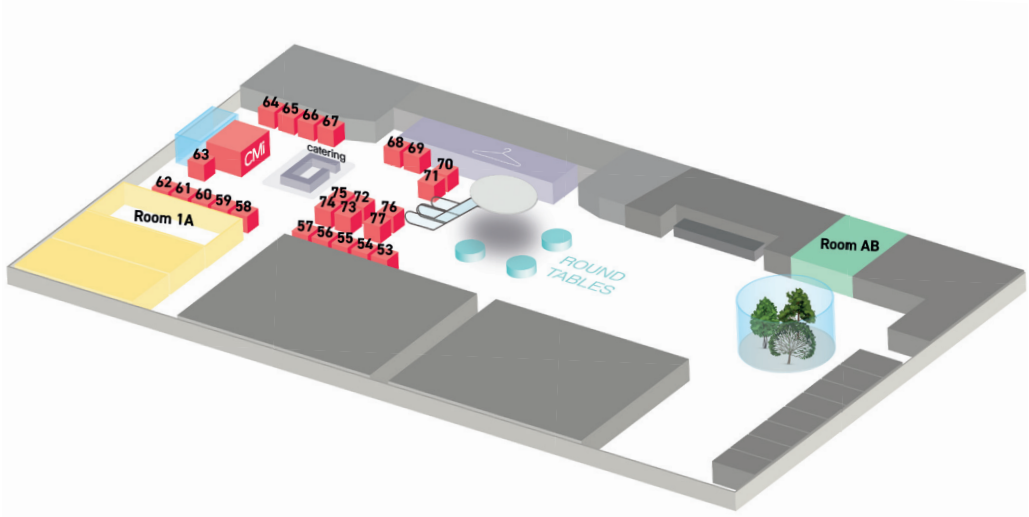
Exhibitor's Parallel Program — Lower Floor Level

11:30	GenISys GmbH — Optimizing Fabrication of Photonics and Plasmonic Devices	Room 1A [O1]	Oral
	ASML Research, ASML Applications — Welcome to ASML	Room AB [W1]	Workshop
11:45	Carl Zeiss, Gloor Instruments AG — Touching the Limits in Optical and Electron Microscopy	Room 1A [O2]	Oral
12:00	Nanoscribe GmbH & Co.KG — Pushing the Limits of 3D Microfabrication: Advances with Nanoscribe	Room 1A [O3]	Oral
12:15	LUNCH BREAK		
12:45	GenISys GmbH — Advanced SEM Metrology Applications Using InSPEC	Room AB [W2]	Workshop
13:30	Lam Research SAS, Lam Research Int. Sàrl — Proving what's possible at Lam Research	Room 1A [O4]	Oral
13:45	KLA Instruments Group — Thickness-Dependent Stress Evolution in ITO Thin Films	Room 1A [O5]	Oral
14:00	Heidelberg Instruments Mikrotechnologie GmbH — The MLA 150: History, Present and Future of Maskless Aligner Technology	Room 1A [O6]	Oral
14:15	scia Systems GmbH — LN-based PICs: Novel techniques for structuring & yield improvements with ion beam processing	Room 1A [O7]	Oral
	Park Systems — Advanced correlative measurement using automated Fx200 AFM	Room AB [W3]	Workshop
15:00	COFFEE BREAK		
15:30	FabuBlox Inc. — FabuBlox: From Process Design to Enabling the Next Generation of Intelligent, High-Flexibility Fab Ecosystems	Room 1A [O8]	Workshop Oral
	ASML Research, ASML Applications — Welcome to ASML	Room AB [W4]	Workshop
15:45	EV Group — Heterogeneous Wafer Bonding	Room 1A [O9]	Oral

Exhibitor's List STCC plan — Lower Floor Level

A	76	Alliance EPFL
	68	AMO GmbH
B	70	Bovard AG
C	57	Carl Zeiss AG x Gloor Instruments
	56	Confovis GmbH
E	55	Electron Mec
F	61	Fabublox
	54	FC'INNOV
	62	FCBG Fondation Campus Biotech
	67	Focuslight Switzerland SA
G	59	GAS Insights GmbH
H	75	Heidelberg Instruments Mikrotechnik GmbH
I	77	Idonus
	53	INL
J	66	JEOL (Europe) SAS
L	71	Ligentec
	73	Lyncée Tec
N	58	Nanosurf
P	72	Park Systems Europe GmbH
S	74	Sensirion AG
	60	Silatech SA
	63	Swiss Chip Alliance
	65	SwissChips
T	64	Tousimis
V	69	Veeco Instruments

Room 1A	Oral
Room AB	Workshop



STCC Lower Floor Plan

Exhibitors' Parallel Technical Talk Abstract Program

O Oral
W Workshop

[O1] Optimizing Fabrication of Photonics and Plasmonic Devices: Software Solutions for Lithography and Metrology.

We present advanced software solutions tailored to optimize fabrication of photonic and plasmonic devices employing electron beam lithography. These solutions are designed to improve line-edge roughness and shape fidelity of fabricated structures, while providing automated image acquisition, inspection and comprehensive metrology for full process characterization.

D. Titko, A. Peyyety, S. Bauerdick, K. Gieb
GenISys GmbH, Unterhaching (DE)

[W1] Welcome to ASML

Introduction to ASML: Company, Lithography, Products, Technology.

L. Vanherpe[1], J. Beltman[2]
1 ASML Research, Veldhoven (NL)
2 ASML Applications, Grenoble (FR)

[O2] Touching the limits in optical and electron microscopy.

As structures in semiconductor samples are becoming smaller and smaller, the imaging and analysis side is challenged by physical barriers. New development of Zeiss light microscope and electron microscopy are presented and time constraints – from hardware solution such as new FIB system to software to use AI supported workflows.

R. Jankele[3], H. Brandenberger[4]
3 Carl Zeiss CH, Feldbach (CH)
4 Gloor Instruments, Opfikon (CH)

[O3] Pushing the Limits of 3D Microfabrication: Advances with Nanoscribe

Nanoscribe's high-precision 3D microfabrication technologies are accelerating innovation across photonics, optics, MEMS and life sciences. This presentation outlines Nanoscribe's latest technological advancements, improved workflows, and industrialization pathways, showing how these developments empower researchers and companies to create high-performance micro-components with unprecedented precision and throughput.

A. Legant
Nanoscribe GmbH & Co.KG,
Eggenstein-Leopoldshafen (DE)

[W2] Advanced SEM Metrology Applications Using InSPEC

We present here an automated scanning electron microscopy methodology for quantitative characterization of photonic structures and metamaterials. The approach combines layout-based navigation, alignment, and autofocus to enable repeated and large sampling across the wafer. Measurements show high-throughput acquisition, consistent critical dimension (CD) data, and statistical analysis capabilities suitable for photonic structures design, fabrication optimization, and process monitoring.

A. Peyyety, D. Titko, S. Bauerdick, K. Gieb
GenISys GmbH, Unterhaching (DE)

[O4] Proving what's possible at Lam Research

Lam Research is a global leader in wafer fabrication equipment and services for high volume advanced CMOS manufacturing. We will introduce our company, touch on AI-enabling process trends, and how collaboration helps Lam teams to go beyond possible in semiconductor manufacturing.

A. Morel[5], A. Filippo[6]
5 Lam Research SAS, Meylan (FR)
6 Lam Research Intl. Sàrl Neuchâtel, (CH)

[O5] Thickness-Dependent Stress Evolution in ITO Thin Films

Stress control in indium tin oxide (ITO) films is essential for reliable device integration. This presentation reports a quantitative study of thickness-dependent stress in sputtered ITO films, combining wafer-bow measurements with optical and surface metrology to link stress evolution to grain growth and process conditions.

D. Weill
KLA Instruments Group, Unterhaching (DE)

[O6] The MLA 150: History, Present and Future of Maskless Aligner Technology

The MLA 150 has shaped maskless aligner technology for over a decade. This talk reviews its evolution, key innovations, and present-day capabilities, including enhanced resolution, automation, and workflow integration. Looking ahead, we outline future developments that will further expand performance, accessibility, and application versatility in modern microfabrication.

B. Stender
Heidelberg Instruments Mikrotechnologie GmbH, Heidelberg (DE)

[O7] LN-based PICs: Novel techniques for structuring and yield improvements with ion beam processing

Lithium niobate photonic integrated circuits require high-quality structuring beyond plasma etching limits. Ion beam etching and trimming enable precise material removal, smooth surfaces, and reduced optical losses. These techniques improve geometry control, yield, and design flexibility. scia Mill 200 and Trim 200 technologies enable advanced structuring strategies, with localized trimming and defect correction improving device uniformity and fabrication yield.

M. Lötsch, R. Metznera
scia Systems GmbH,
Chemnitz (DE)

[W3] Advanced correlative measurement using automated Fx200 AFM

Park Systems AFM solutions enable advanced nanoscale characterization of graphene on Silicon carbide. By integrating KPFM, C-AFM, and sMIM on a single automated platform, users achieve reliable, high-resolution measurements of surface potential, conductivity, and layer structure, accelerating analysis of complex 2D materials and improving productivity in research and device development.

M. Lefevre, R. Bourrellier
Park Systems, Orsay (FR)

[O8] FabuBlox: From Process Design to Ena bling the Next Generation of Intelligent, HighFlexibility Fab Ecosystems

FabuBlox introduces a unified platform for version-controlled process design and layer stack emulation combined with intelligent fab management. Enhanced by early-stage agentic AI capabilities, FabuBlox streamlines operations, reduces tool downtime, and improves reproducibility in high-flexibility fab environments. This is achieved by standardizing process onboarding, enforcing recipe parameter rules, managing tool capabilities and calibrations, and automating contamination control.

J. Tiepelt
FabuBlox, Inc., Boston, MA (USA)

[W4] Welcome to ASML

Introduction to ASML: Company, Lithography, Products, Technology.

L. Vanherpe[1], J. Beltman[2]
1 ASML Research, Veldhoven (NL)
2 ASML Applications, Grenoble (FR)

[O9] Heterogeneous Wafer Bonding

Wafer bonding has become a foundational technology in modern semiconductor devices, enabling heterogeneous system architectures in which different chips and materials are combined at the wafer level into highly integrated systems. This presentation will focus on plasma-activated fusion bonding, highlighting its process principles and illustrating its applicability through selected use cases. In addition, the presentation will discuss high-vacuum, oxide-free wafer bonding, a technology that enables conductive bond interfaces and is particularly well suited for heterogeneous material integration at low or even room temperature.

O. Bobenstetter, C. Warmuth
EV Group, Sankt Florian am Inn (AT)